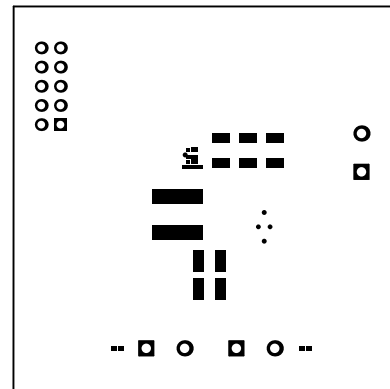
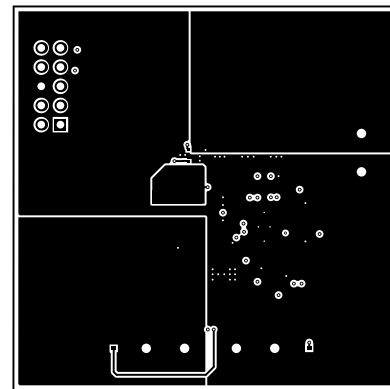


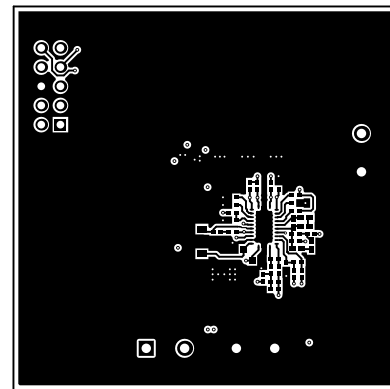
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20084	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Overlay	GENERATED : 12/8/2016 2:48:09 PM	TEXAS INSTRUMENTS	



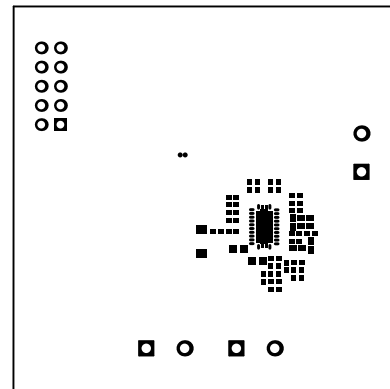
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20084	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 12/8/2016 2:48:09 PM	TEXAS INSTRUMENTS	



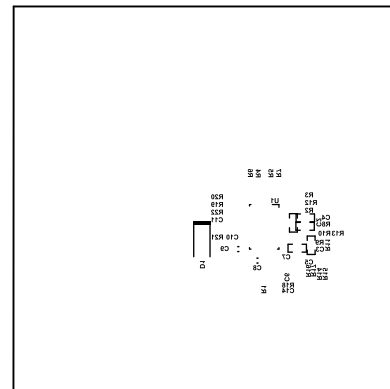
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20084	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 12/8/2016 2:48:10 PM	TEXAS INSTRUMENTS	



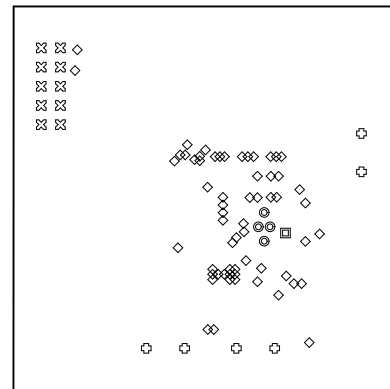
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20084	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 12/8/2016 2:48:10 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20084	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/8/2016 2:48:11 PM	TEXAS INSTRUMENTS	

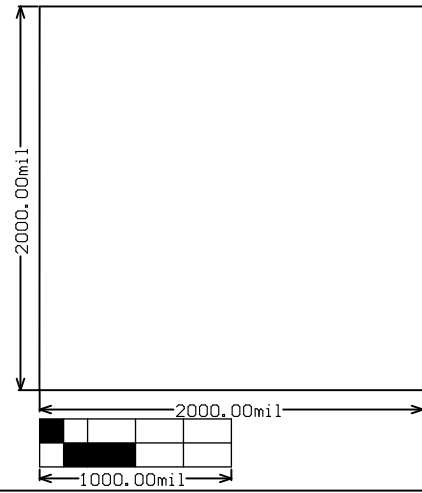


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20084	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 12/8/2016 2:48:11 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
●	4	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
■	1	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
◇	61	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	10	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	6	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
	82 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20084	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 12/8/2016	2:48:12 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20084	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 12/8/2016 2:48:12 PM	TEXAS INSTRUMENTS	

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